



Final Product/Process Change Notification

Document # : FPCN21204XC

Issue Date: 10 November 2016

Title of Change:	Optical Device Chip Scale Package (ODCSP) site change from Gunma, Japan to Niigata, Japan and Dicing site change from Shenzhen, China to Tarlac, Philippines		
Proposed first ship date:	15 May 2017 or earlier upon approval due to shortage of product		
Contact information:	Contact your local ON Semiconductor Sales Office or <Hiroshi.Kojima@onsemi.com>		
Samples:	Contact your local ON Semiconductor Sales Office		
Additional Reliability Data:	Contact your local ON Semiconductor Sales Office or <Satoru.Fujinuma@onsemi.com>		
Type of notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact <PCN.Support@onsemi.com>.		
Change Part Identification:	Products manufactured at Niigata and Tarlac will be printed Date Code from 1705 on shipping MPN label.		
Change category:	<input type="checkbox"/> Wafer Fab Change <input checked="" type="checkbox"/> Assembly Change <input type="checkbox"/> Test Change <input type="checkbox"/> Other _____		
Change Sub-Category(s):	<div style="display: flex; flex-wrap: wrap;"> <div style="width: 33%;"> <input checked="" type="checkbox"/> Manufacturing Site Change/Addition <input type="checkbox"/> Manufacturing Process Change </div> <div style="width: 33%;"> <input type="checkbox"/> Material Change <input type="checkbox"/> Product specific change </div> <div style="width: 33%;"> <input type="checkbox"/> Datasheet/Product Doc change <input type="checkbox"/> Shipping/Packaging/Marking <input type="checkbox"/> Other: _____ </div> </div>		
Sites Affected:	<input type="checkbox"/> All site(s) <input type="checkbox"/> not applicable <input checked="" type="checkbox"/> ON Semiconductor site(s) : ON Gunma, Japan ON Niigata, Japan ON Tarlac City, Philippines ON Shenzhen, China <input type="checkbox"/> External Foundry/Subcon site(s)		
Description and Purpose:			
To continuously supply products and increase our supply capacity to support increased demand, the Optical Device Chip Scale Package (ODCSP) location will move from Gunma, Japan to Niigata, Japan and dicing site location will move from Shenzhen, China to Tarlac city, Philippines. All equipment and most personnel were transferred from Gunma to Niigata site and most equipment was transferred from Shenzhen to Tarlac site. The Niigata and Tarlac site are ISO/TS16949 certified.			

**Reliability Data Summary:**

QV DEVICE NAME LV0318XA-NH

PACKAGE ODCSP16

Test	Specification	Condition	Interval	Results
HTOL	EIAJ ED-4701/100	Ta= 70°C , Vcc = operating max	1008 hrs	0/231
HTSL	EIAJ ED-4701/200	Ta= 100°C	1008 hrs	0/231
TC	EIAJ ED-4701/100	Ta= -40°C to +100°C	100 cyc	0/231
THB	EIAJ ED-4701/100	60°C, 90% RH, Vcc = recommended	1008 hrs	0/231

Electrical Characteristic Summary:

There is no change in the electrical performance. Datasheet specifications remain unchanged.

List of affected Standard Parts:

Part Number	Qualification Vehicle
LV0221CS-TLM-H	LV0318XA-NH
LV0229XA-NH	LV0318XA-NH
LA0151CS-TLM-E	LV0318XA-NH